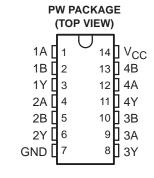
SN74LV08A-Q1 QUADRUPLE 2-INPUT POSITIVE-AND GATE

SCLS465C - FEBRUARY 2003 - REVISED JANUARY 2008



- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)>2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Supports Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



description/ordering information

This quadruple 2-input positive-AND gate is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV08A performs the Boolean function $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION†

TA	PACKA	\GE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP - PW	Tape and reel	SN74LV08ATPWRQ1	LV08ATQ

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Н	Н
L	Χ	L
Х	L	L



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

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SCLS465C - FEBRUARY 2003 - REVISED JANUARY 2008

logic diagram, each gate (positive logic)

Δ	 $\overline{}$	
_	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	v
D	 	•
0		

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 3)	113°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2	5.5	V	
		V _{CC} = 2 V	1.5			
V	High level input valte as	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		V	
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	V _{CC} ×0.7		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} ×0.7			
		V _{CC} = 2 V		0.5		
V/		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V	
V_{IL}	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$VCC \times 0.3$		
V_{I}	Input voltage		0	5.5	V	
٧o	Output voltage		0	VCC	V	
		V _{CC} = 2 V		-50	μΑ	
	High-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		
ЮН		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		
		V _{CC} = 2 V		50	μΑ	
1	Lavy lavyal avidavid avima at	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		
loL	Low-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		
TA	Operating free-air temperature		-40	105	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	MIN	TYP	MAX	UNIT
	$I_{OH} = -50 \mu\text{A}$		2 V to 5.5 V	V _{CC} -0.1			
	$I_{OH} = -2 \text{ mA}$		2.3 V	2			.,
VOH	$I_{OH} = -6 \text{ mA}$		3 V	2.48			V
	I _{OH} = -12 mA		4.5 V	3.8			
	I _{OL} = 50 μA		2 V to 5.5 V			0.1	
	I _{OL} = 2 mA		2.3 V			0.4	.,
VOL	I _{OL} = 6 mA		3 V			0.44	V
	I _{OL} = 12 mA		4.5 V			0.55	
Ц	V _I = 5.5 V or GND		0 to 5.5 V			±1	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V			20	μΑ
l _{off}	V_I or $V_O = 0$ to 5.5 V		0			5	μΑ
C.	V V 0ND		3.3 V		3.3		~F
Ci	$V_I = V_{CC}$ or GND		5 V		3.3		pF

SN74LV08A-Q1 QUADRUPLE 2-INPUT POSITIVE-AND GATE

SCLS465C - FEBRUARY 2003 - REVISED JANUARY 2008

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	չ = 25°C	;		MAY	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
^t pd	A or B	Υ	C _L = 50 pF		7.5	12.3	1	16	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	չ = 25°C	;	MAIN	MAY	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN MAX	WAX	UNIT
t _{pd}	A or B	Υ	C _L = 50 pF		5.5	7.9	1	12	ns

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

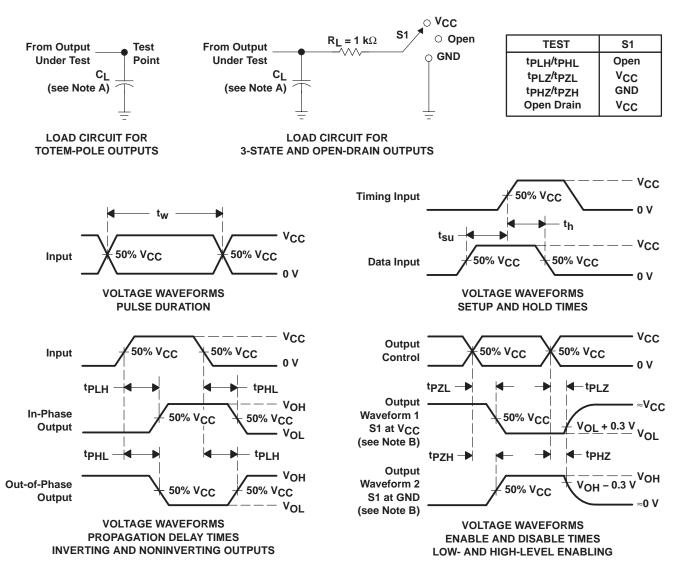
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V
VOL(V)	Quiet output, minimum dynamic VOL		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		3.1		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL} (D)	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
	Davis discination associtance	C. 50 mE & 40 MHz	3.3 V	8	
1	pd Power dissipation capacitance	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	5 V	10	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 3 ns, $t_f \leq$ 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







ti.com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV08ATPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV08ATPWRQ1	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV08A-Q1:

Catalog: SN74LV08A

Enhanced Product: SN74LV08A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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